

General Description

These N-Channel enhancement mode power field effect transistors uses advanced trench Technology, which provides low on-state resistance, high switching performance and excellent quality. These devices are well suited for high efficiency switching DC/DC converters, switch mode power supplies, DC-AC converters for uninterrupted power supplies and motor controls.

Features

- 16A, 250V, $R_{DS(on)} = 0.245\Omega$ @ $V_{GS} = 10V$
- 100% avalanche tested
- Fast Switching
- Improved dv/dt capability

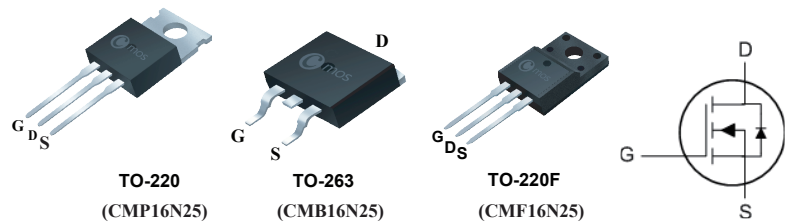
Product Summary

BVDSS	RDSON	ID
250V	0.245Ω	16A

Applications

- Switch mode power supplies (SMPS)
- PWM Motor Controls
- DC-DC converters

TO-220/263/220F Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	220/263	220F	Units
V_{DS}	Drain-Source Voltage	250		V
V_{GS}	Gate-Source Voltage	± 30		V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current	16	16*	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current	10	10*	A
I_{DM}	Pulsed Drain Current ^(Note 1)	50	50*	A
EAS	Single Pulse Avalanche Energy ^(Note 2)	360		mJ
dv/dt	Peak Diode Recovery dv/dt ^(Note 3)	5.5		V/ns
$P_D @ T_C = 25^\circ C$	Total Power Dissipation	140	45	W
T_{STG}	Storage Temperature Range	-55 to 150		$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150		$^\circ C$

* Drain current limited by maximum junction temperature.

Thermal Data

Symbol	Parameter	220/263	220F	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient	62.5	62.5	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-case	0.9	2.89	$^\circ C/W$

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V$, $I_D=250\mu A$	250	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BVDSS Temperature Coefficient	Reference to 25°C , $I_D=250\mu A$	---	0.31	---	V/ $^\circ\text{C}$
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10V$, $I_D=8A$	---	---	0.245	Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250\mu A$	2	---	4	V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=250V$, $V_{GS}=0V$	---	---	10	μA
		$V_{DS}=200V$, $V_{GS}=0V$, $TC=125^\circ\text{C}$	---	---	100	
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 30V$, $V_{DS}=0V$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{DS}=15V$, $I_D=8A$ (Note 4)	---	11	---	S
Q_g	Total Gate Charge	$I_D=16A$	---	40	52	nC
Q_{gs}	Gate-Source Charge	$V_{DS}=200V$	---	5.5	---	
Q_{gd}	Gate-Drain Charge	$V_{GS}=10V$ (Note 4, 5)	---	23	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=125V$	---	15	---	ns
T_r	Rise Time	$I_D=16A$	---	130	---	
$T_{d(off)}$	Turn-Off Delay Time	$R_G=25\Omega$	---	135	---	
T_f	Fall Time	(Note 4, 5)	---	105	---	
C_{iss}	Input Capacitance	$V_{DS}=25V$, $V_{GS}=0V$, $f=1\text{MHz}$	---	4200	---	pF
C_{oss}	Output Capacitance		---	170	---	
C_{rss}	Reverse Transfer Capacitance		---	70	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	$V_G=V_D=0V$, Force Current	---	---	16	A
I_{SM}	Pulsed Source Current		---	---	50	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0V$, $I_S=15A$, $T_J=25^\circ\text{C}$	---	---	1.5	V
t_{rr}	Reverse Recovery Time	$V_{GS}=0V$, $I_S=16A$, $T_J=25^\circ\text{C}$	---	260	---	ns
Q_{rr}	Reverse Recovery Charge	$di/dt=100A/\mu s$	---	2.47	---	μC

Note :

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. $L = 1\text{mH}$, $I_{AS} = 27A$, $V_{DD} = 50V$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 16A$, $di/dt \leq 300A/\mu s$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
4. Pulse Test Pulsewidth $\leq 300\mu s$, Duty cycle $\leq 2\%$
5. Essentially independent of operating temperature

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